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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf819t-i-ss

PIC16F818/819

TABLE 1-2: PIC16F818/819 PINOUT DESCRIPTIONS (CONTINUED)

Pin Name	PDIP/ SOIC Pin#	SSOP Pin#	QFN Pin#	I/O/P Type	Buffer Type	Description
RB0/INT RB0 INT	6	7	7	I/O I	TTL ST ⁽¹⁾	PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. Bidirectional I/O pin. External interrupt pin.
RB1/SDI/SDA RB1 SDI SDA	7	8	8	I/O I I/O	TTL ST ST	Bidirectional I/O pin. SPI data in. I ² C™ data.
RB2/SDO/CCP1 RB2 SDO CCP1	8	9	9	I/O O I/O	TTL ST ST	Bidirectional I/O pin. SPI data out. Capture input, Compare output, PWM output.
RB3/CCP1/PGM RB3 CCP1 PGM	9	10	10	I/O I/O I	TTL ST ST	Bidirectional I/O pin. Capture input, Compare output, PWM output. Low-Voltage ICSP™ Programming enable pin.
RB4/SCK/SCL RB4 SCK SCL	10	11	12	I/O I/O I	TTL ST ST	Bidirectional I/O pin. Interrupt-on-change pin. Synchronous serial clock input/output for SPI. Synchronous serial clock input for I ² C.
RB5/ \overline{SS} RB5 \overline{SS}	11	12	13	I/O I	TTL TTL	Bidirectional I/O pin. Interrupt-on-change pin. Slave select for SPI in Slave mode.
RB6/T1OSO/T1CKI/PGC RB6 T1OSO T1CKI PGC	12	13	15	I/O O I I	TTL ST ST ST ⁽²⁾	Interrupt-on-change pin. Timer1 Oscillator output. Timer1 clock input. In-circuit debugger and ICSP programming clock pin.
RB7/T1OSI/PGD RB7 T1OSI PGD	13	14	16	I/O I I	TTL ST ST ⁽²⁾	Interrupt-on-change pin. Timer1 oscillator input. In-circuit debugger and ICSP programming data pin.
Vss	5	5, 6	3, 5	P	–	Ground reference for logic and I/O pins.
VDD	14	15, 16	17, 19	P	–	Positive supply for logic and I/O pins.

Legend: I = Input O = Output I/O = Input/Output P = Power
– = Not used TTL = TTL Input ST = Schmitt Trigger Input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

3: This buffer is a Schmitt Trigger input when configured in RC Oscillator mode and a CMOS input otherwise.

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2.2 Data Memory Organization

The data memory is partitioned into multiple banks that contain the General Purpose Registers and the Special Function Registers. Bits RP1 (Status<6>) and RP0 (Status<5>) are the bank select bits.

RP1:RP0	Bank
00	0
01	1
10	2
11	3

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are the General Purpose Registers, implemented as static RAM. All implemented banks contain SFRs. Some “high use” SFRs from one bank may be mirrored in another bank for code reduction and quicker access (e.g., the Status register is in Banks 0-3).

Note: EEPROM data memory description can be found in Section 3.0 “Data EEPROM and Flash Program Memory” of this data sheet.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly or indirectly through the File Select Register, FSR.

FIGURE 4-2: CERAMIC RESONATOR OPERATION (HS OR XT OSC CONFIGURATION)

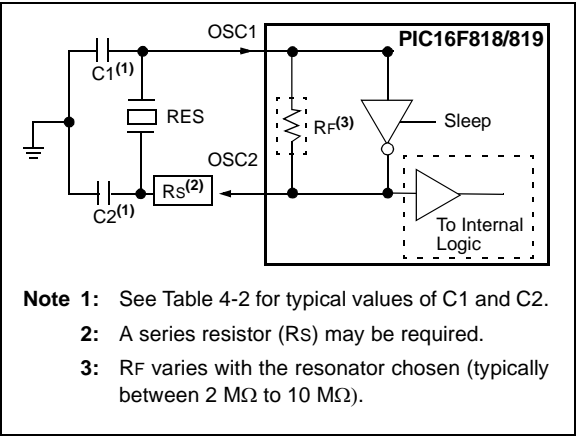


TABLE 4-2: CERAMIC RESONATORS (FOR DESIGN GUIDANCE ONLY)

Typical Capacitor Values Used:			
Mode	Freq	OSC1	OSC2
XT	455 kHz	56 pF	56 pF
	2.0 MHz	47 pF	47 pF
	4.0 MHz	33 pF	33 pF
HS	8.0 MHz	27 pF	27 pF
	16.0 MHz	22 pF	22 pF

Capacitor values are for design guidance only.

These capacitors were tested with the resonators listed below for basic start-up and operation. These values were not optimized.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application.

See the notes following this table for additional information.

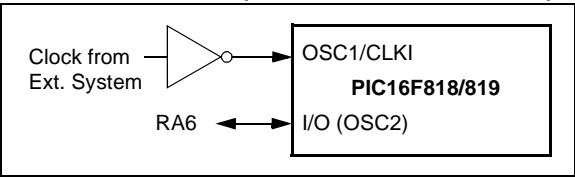
Note: When using resonators with frequencies above 3.5 MHz, the use of HS mode rather than XT mode is recommended. HS mode may be used at any VDD for which the controller is rated. If HS is selected, it is possible that the gain of the oscillator will overdrive the resonator. Therefore, a series resistor should be placed between the OSC2 pin and the resonator. As a good starting point, the recommended value of Rs is 330Ω.

4.3 External Clock Input

The ECIO Oscillator mode requires an external clock source to be connected to the OSC1 pin. There is no oscillator start-up time required after a Power-on Reset or after an exit from Sleep mode.

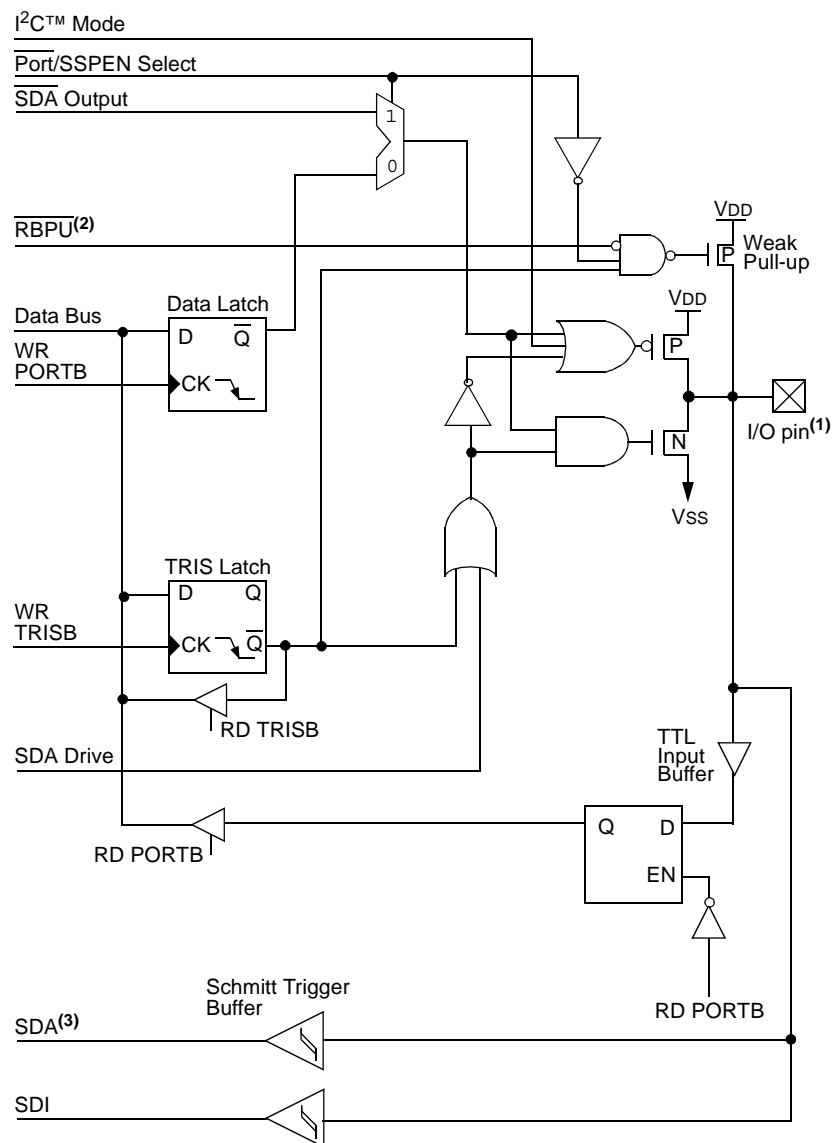
In the ECIO Oscillator mode, the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 4-3 shows the pin connections for the ECIO Oscillator mode.

FIGURE 4-3: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



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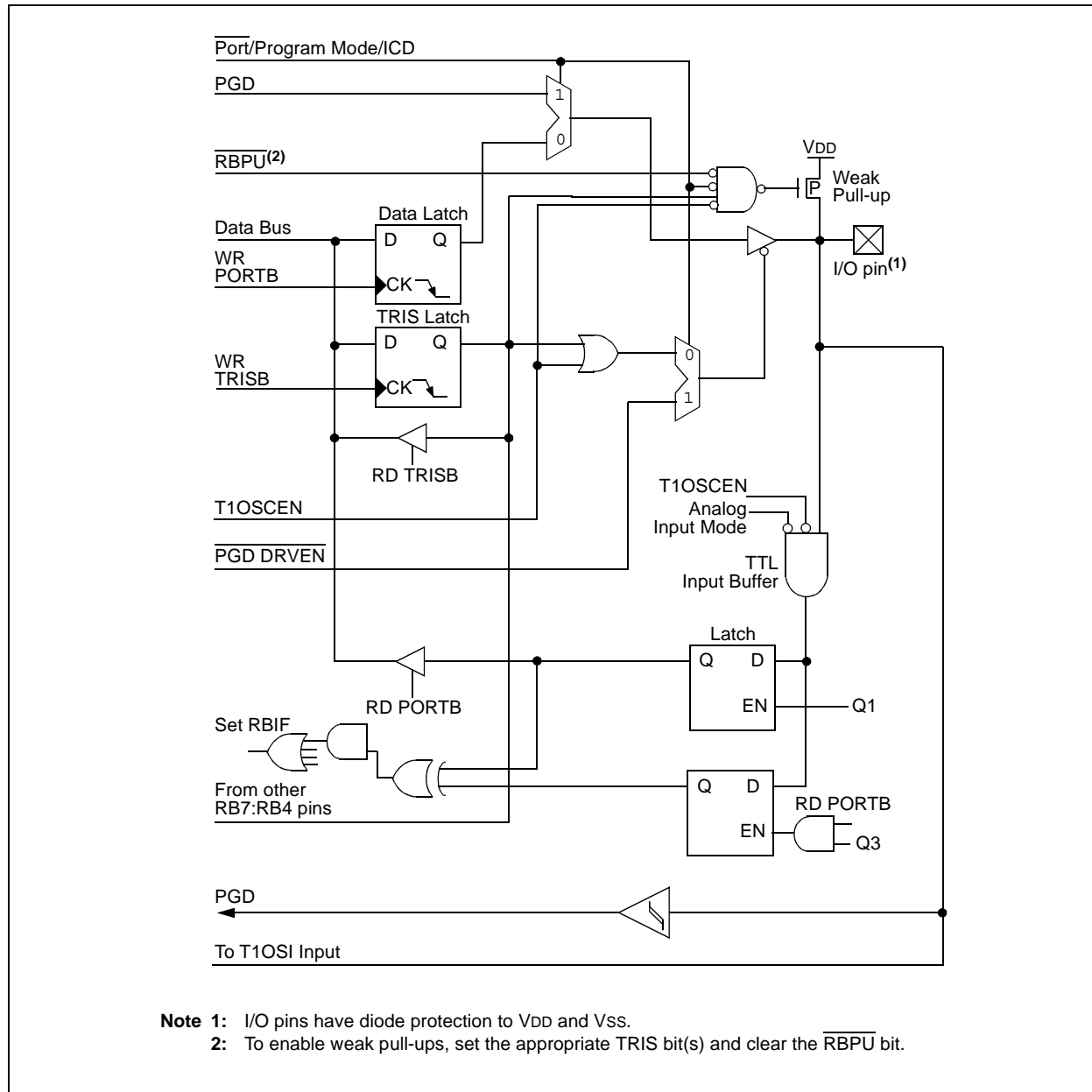
FIGURE 5-9: BLOCK DIAGRAM OF RB1 PIN



- Note 1:** I/O pins have diode protection to VDD and VSS.
Note 2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit.
Note 3: The SDA Schmitt Trigger conforms to the I²C specification.

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FIGURE 5-15: BLOCK DIAGRAM OF RB7 PIN



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6.3 Using Timer0 with an External Clock

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, it is necessary for T0CKI to be high for at least 2 TOSC (and a small RC delay of 20 ns) and low for at least 2 TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

6.4 Prescaler

There is only one prescaler available which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. A prescaler assignment for the

Timer0 module means that there is no prescaler for the Watchdog Timer and vice versa. This prescaler is not readable or writable (see Figure 6-1).

The PSA and PS2:PS0 bits (OPTION_REG<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDI instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

Note: Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count but will not change the prescaler assignment.

REGISTER 6-1: OPTION_REG: OPTION REGISTER (ADDRESS 81h, 181h)

	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	RBPUP	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
	bit 7							bit 0
bit 7	RBPUP: PORTB Pull-up Enable bit 1 = PORTB pull-ups are disabled 0 = PORTB pull-ups are enabled by individual port latch values							
bit 6	INTEDG: Interrupt Edge Select bit 1 = Interrupt on rising edge of RB0/INT pin 0 = Interrupt on falling edge of RB0/INT pin							
bit 5	T0CS: TMR0 Clock Source Select bit 1 = Transition on T0CKI pin 0 = Internal instruction cycle clock (CLKO)							
bit 4	T0SE: TMR0 Source Edge Select bit 1 = Increment on high-to-low transition on T0CKI pin 0 = Increment on low-to-high transition on T0CKI pin							
bit 3	PSA: Prescaler Assignment bit 1 = Prescaler is assigned to the WDT 0 = Prescaler is assigned to the Timer0 module							
bit 2-0	PS2:PS0: Prescaler Rate Select bits							
	Bit Value	TMR0 Rate	WDT Rate					
	000	1 : 2	1 : 1					
	001	1 : 4	1 : 2					
	010	1 : 8	1 : 4					
	011	1 : 16	1 : 8					
	100	1 : 32	1 : 16					
	101	1 : 64	1 : 32					
	110	1 : 128	1 : 64					
	111	1 : 256	1 : 128					

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

Note: To avoid an unintended device Reset, the instruction sequence shown in the "PIC® Mid-Range MCU Family Reference Manual" (DS33023) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

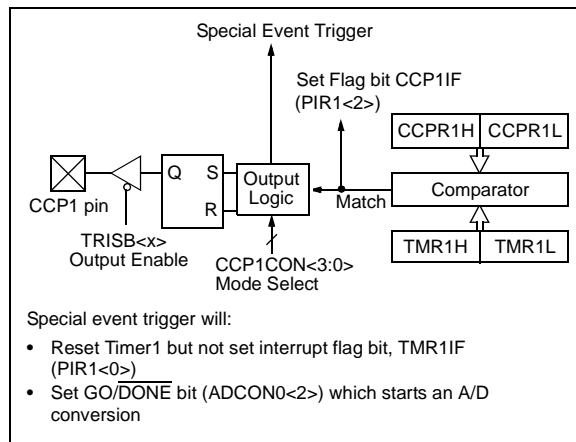
9.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the CCP1 pin is:

- Driven high
- Driven low
- Remains unchanged

The action on the pin is based on the value of control bits, CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit CCP1IF is set.

FIGURE 9-2: COMPARE MODE OPERATION BLOCK DIAGRAM



9.2.1 CCP PIN CONFIGURATION

The user must configure the CCP1 pin as an output by clearing the TRISB<x> bit.

Note 1: Clearing the CCP1CON register will force the CCP1 compare output latch to the default low level. This is not the data latch.

2: The TRISB bit (2 or 3) is dependent upon the setting of configuration bit 12 (CCPMX).

9.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

9.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

9.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated that may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair and starts an A/D conversion (if the A/D module is enabled). This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

Note: The special event trigger from the CCP1 module will not set interrupt flag bit, TMR1IF (PIR1<0>).

TABLE 9-2: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Bh,8Bh 10BH,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	-0-- 0000	-0-- 0000
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	-0-- 0000	-0-- 0000
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYN	TMR1CS	TMR1ON	--00 0000	--uu uuuu
15h	CCPR1L	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by Capture and Timer1.

10.3.1 SLAVE MODE

In Slave mode, the SCL and SDA pins must be configured as inputs (TRISB<4,1> set). The SSP module will override the input state with the output data when required (slave-transmitter).

When an address is matched, or the data transfer after an address match is received, the hardware automatically will generate the Acknowledge (ACK) pulse and then load the SSPBUF register with the received value currently in the SSPSR register.

Either or both of the following conditions will cause the SSP module not to give this ACK pulse:

- a) The Buffer Full bit, BF (SSPSTAT<0>), was set before the transfer was received.
- b) The overflow bit, SSPOV (SSPCON<6>), was set before the transfer was received.

In this case, the SSPSR register value is not loaded into the SSPBUF but bit, SSPIF (PIR1<3>), is set. Table 10-2 shows what happens when a data transfer byte is received, given the status of bits BF and SSPOV. The shaded cells show the condition where user software did not properly clear the overflow condition. Flag bit BF is cleared by reading the SSPBUF register while bit SSPOV is cleared through software.

The SCL clock input must have a minimum high and low for proper operation. The high and low times of the I²C specification, as well as the requirement of the SSP module, are shown in timing parameter #100 and parameter #101.

10.3.1.1 Addressing

Once the SSP module has been enabled, it waits for a Start condition to occur. Following the Start condition, the eight bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match and the BF and SSPOV bits are clear, the following events occur:

- a) The SSPSR register value is loaded into the SSPBUF register.
- b) The Buffer Full bit, BF, is set.
- c) An $\overline{\text{ACK}}$ pulse is generated.
- d) SSP Interrupt Flag bit, SSPIF (PIR1<3>), is set (interrupt is generated if enabled) – on the falling edge of the ninth SCL pulse.

In 10-bit Address mode, two address bytes need to be received by the slave device. The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit R/W (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address, the first byte would equal '1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address.

The sequence of events for 10-bit address is as follows, with steps 7-9 for slave-transmitter:

1. Receive first (high) byte of address (bits SSPIF, BF and bit UA (SSPSTAT<1>) are set).
2. Update the SSPADD register with second (low) byte of address (clears bit UA and releases the SCL line).
3. Read the SSPBUF register (clears bit BF) and clear flag bit, SSPIF.
4. Receive second (low) byte of address (bits SSPIF, BF and UA are set).
5. Update the SSPADD register with the first (high) byte of address; if match releases SCL line, this will clear bit UA.
6. Read the SSPBUF register (clears bit BF) and clear flag bit, SSPIF.
7. Receive Repeated Start condition.
8. Receive first (high) byte of address (bits SSPIF and BF are set).
9. Read the SSPBUF register (clears bit BF) and clear flag bit, SSPIF.

10.3.1.2 Reception

When the R/W bit of the address byte is clear and an address match occurs, the R/W bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register.

When the address byte overflow condition exists, then a no Acknowledge ($\overline{\text{ACK}}$) pulse is given. An overflow condition is indicated if either bit, BF (SSPSTAT<0>), is set or bit, SSPOV (SSPCON<6>), is set.

An SSP interrupt is generated for each data transfer byte. Flag bit, SSPIF (PIR1<3>), must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

10.3.1.3 Transmission

When the R/W bit of the incoming address byte is set and an address match occurs, the R/W bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{\text{ACK}}$ pulse will be sent on the ninth bit and pin RB4/SCK/SCL is held low. The transmit data must be loaded into the SSPBUF register which also loads the SSPSR register. Then pin RB4/SCK/SCL should be enabled by setting bit, CKP (SSPCON<4>). The master device must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master device by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 10-7).

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An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{\text{ACK}}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{\text{ACK}}$), then

the data transfer is complete. When the $\overline{\text{ACK}}$ is latched by the slave device, the slave logic is reset (resets SSPSTAT register) and the slave device then monitors for another occurrence of the Start bit. If the SDA line was low ($\overline{\text{ACK}}$), the transmit data must be loaded into the SSPBUF register which also loads the SSPSR register. Then pin RB4/SCK/SCL should be enabled by setting bit, CKP.

TABLE 10-2: DATA TRANSFER RECEIVED BYTE ACTIONS

Status Bits as Data Transfer is Received		SSPSR → SSPBUF	Generate $\overline{\text{ACK}}$ Pulse	Set bit SSPIF (SSP interrupt occurs if enabled)
BF	SSPOV			
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	No	No	Yes

Note 1: Shaded cells show the conditions where the user software did not properly clear the overflow condition.

FIGURE 10-6: I²C™ WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)

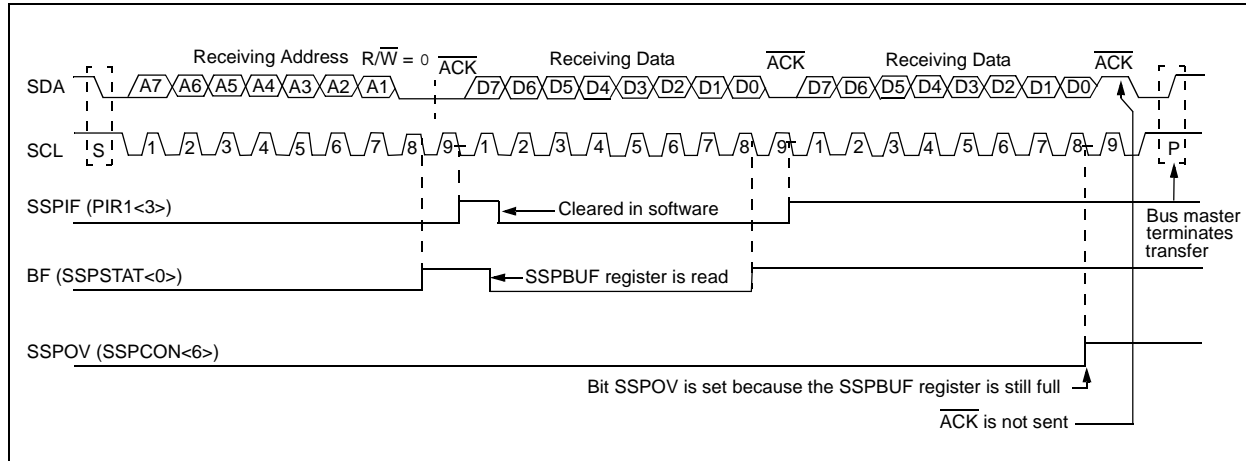
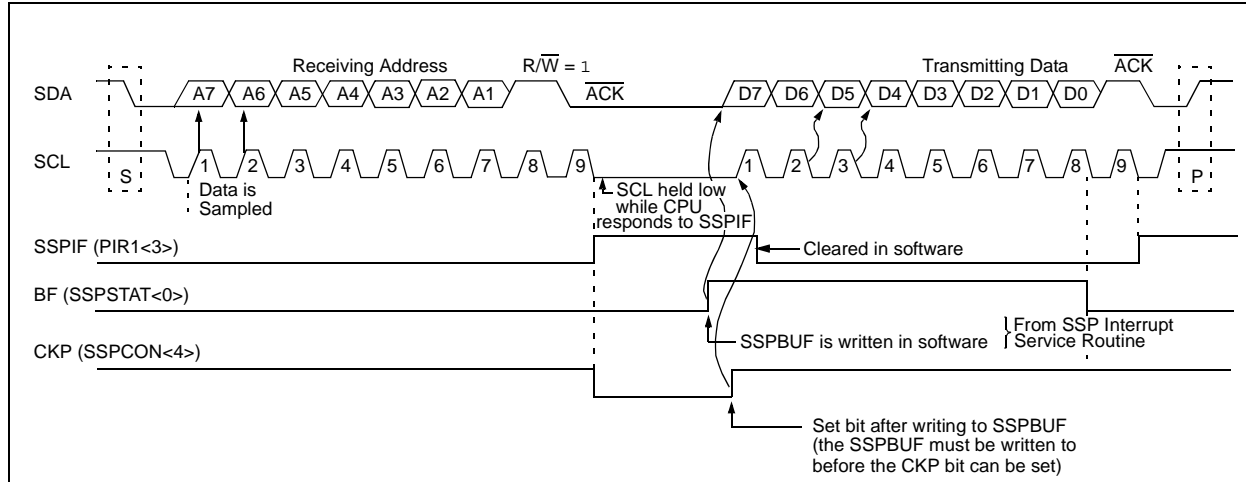


FIGURE 10-7: I²C™ WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



11.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) converter module has five inputs for 18/20 pin devices.

The conversion of an analog input signal results in a corresponding 10-bit digital number. The A/D module has a high and low-voltage reference input that is software selectable to some combination of VDD, VSS, RA2 or RA3.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The A/D module has four registers:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

The ADCON0 register, shown in Register 11-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 11-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/Os.

Additional information on using the A/D module can be found in the "PIC® Mid-Range MCU Family Reference Manual" (DS33023).

REGISTER 11-1: ADCON0: A/D CONTROL REGISTER 0 (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON
bit 7							bit 0

bit 7-6 **ADCS1:ADCS0:** A/D Conversion Clock Select bits

If ADCS2 = 0:

00 = FOSC/2

01 = FOSC/8

10 = FOSC/32

11 = FRC (clock derived from the internal A/D module RC oscillator)

If ADCS2 = 1:

00 = FOSC/4

01 = FOSC/16

10 = FOSC/64

11 = FRC (clock derived from the internal A/D module RC oscillator)

bit 5-3 **CHS2:CHS0:** Analog Channel Select bits

000 = Channel 0 (RA0/AN0)

001 = Channel 1 (RA1/AN1)

010 = Channel 2 (RA2/AN2)

011 = Channel 3 (RA3/AN3)

100 = Channel 4 (RA4/AN4)

bit 2 **GO/DONE:** A/D Conversion Status bit

If ADON = 1:

1 = A/D conversion in progress (setting this bit starts the A/D conversion)

0 = A/D conversion not in progress (this bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1 **Unimplemented:** Read as '0'

bit 0 **ADON:** A/D On bit

1 = A/D converter module is operating

0 = A/D converter module is shut-off and consumes no operating current

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

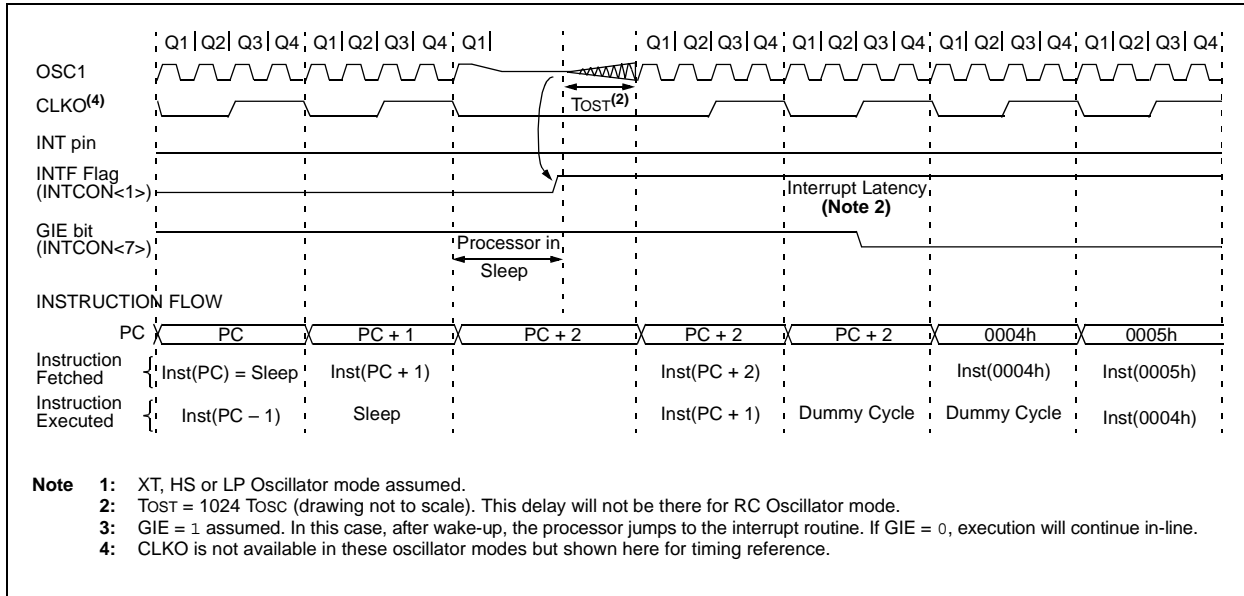
-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

FIGURE 12-9: WAKE-UP FROM SLEEP THROUGH INTERRUPT



12.14 In-Circuit Debugger

When the DEBUG bit in the Configuration Word is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® ICD. When the microcontroller has this feature enabled, some of the resources are not available for general use. Table 12-6 shows which features are consumed by the background debugger.

TABLE 12-6: DEBUGGER RESOURCES

I/O pins	RB6, RB7
Stack	1 level
Program Memory	Address 0000h must be NOP Last 100h words
Data Memory	0x070 (0x0F0, 0x170, 0x1F0) 0x1EB-0x1EF

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to MCLR/VPP, VDD, GND, RB7 and RB6. This will interface to the in-circuit debugger module available from Microchip or one of the third party development tool companies.

12.15 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

12.16 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the four Least Significant bits of the ID location are used.

14.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

14.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, pre-processor, and one-step driver, and can run on multiple platforms.

14.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

14.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

14.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

PIC16F818/819

15.2 DC Characteristics: Power-Down and Supply Current PIC16F818/819 (Industrial, Extended) PIC16LF818/819 (Industrial) (Continued)

PIC16LF818/819 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC16F818/819 (Industrial, Extended)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD) ^(2,3)						
	PIC16LF818/819	72	95	μA	-40°C	VDD = 2.0V	FOSC = 1 MHz (RC Oscillator) ⁽³⁾
		76	90	μA	+25°C		
		76	90	μA	+85°C		
	PIC16LF818/819	138	175	μA	-40°C	VDD = 3.0V	
		136	170	μA	+25°C		
		136	170	μA	+85°C		
	All devices	310	380	μA	-40°C	VDD = 5.0V	
		290	360	μA	+25°C		
		280	360	μA	+85°C		
	Extended devices	350	500	μA	+125°C		
	PIC16LF818/819	270	315	μA	-40°C	VDD = 2.0V	FOSC = 4 MHz (RC Oscillator) ⁽³⁾
		280	310	μA	+25°C		
		285	310	μA	+85°C		
	PIC16LF818/819	460	610	μA	-40°C	VDD = 3.0V	
		450	600	μA	+25°C		
		450	600	μA	+85°C		
	All devices	900	1060	μA	-40°C	VDD = 5.0V	
		890	1050	μA	+25°C		
		890	1050	μA	+85°C		
Extended devices	.920	1.5	mA	+125°C			

Legend: Shading of rows is to assist in readability of the table.

- Note 1:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).
- 2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all I_{DD} measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD};
MCLR = V_{DD}; WDT enabled/disabled as specified.
- 3:** For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be estimated by the formula $I_r = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in k Ω .

TABLE 15-7: I²C™ BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
90*	TSU:STA	Start Condition	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
		Setup Time	400 kHz mode	600	—	—		
91*	THD:STA	Start Condition	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
		Hold Time	400 kHz mode	600	—	—		
92*	TSU:STO	Stop Condition	100 kHz mode	4700	—	—	ns	
		Setup Time	400 kHz mode	600	—	—		
93	THD:STO	Stop Condition	100 kHz mode	4000	—	—	ns	
		Hold Time	400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 15-15: I²C™ BUS DATA TIMING

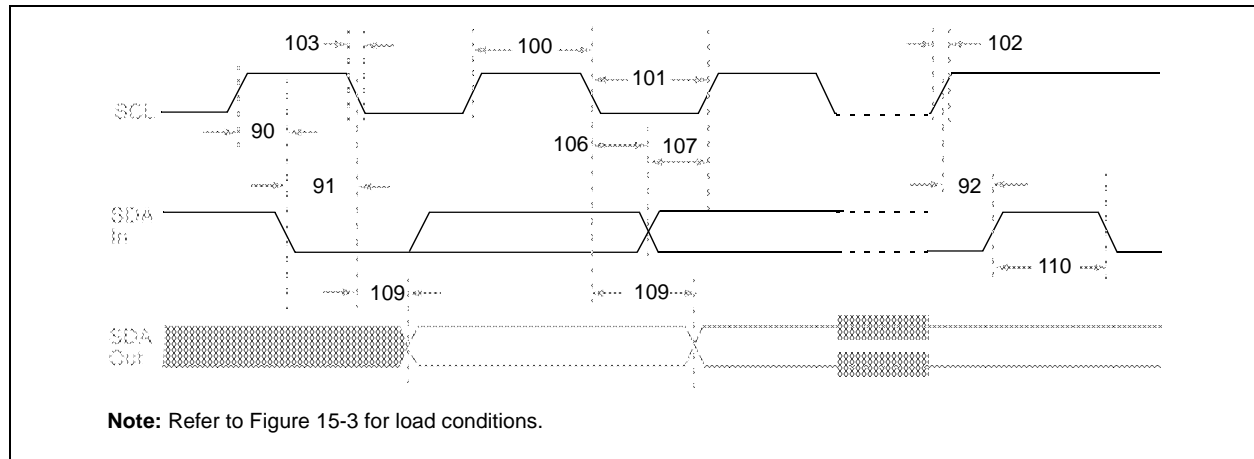


FIGURE 16-21: MINIMUM AND MAXIMUM V_{IN} vs. V_{DD} (TTL INPUT, -40°C TO +125°C)

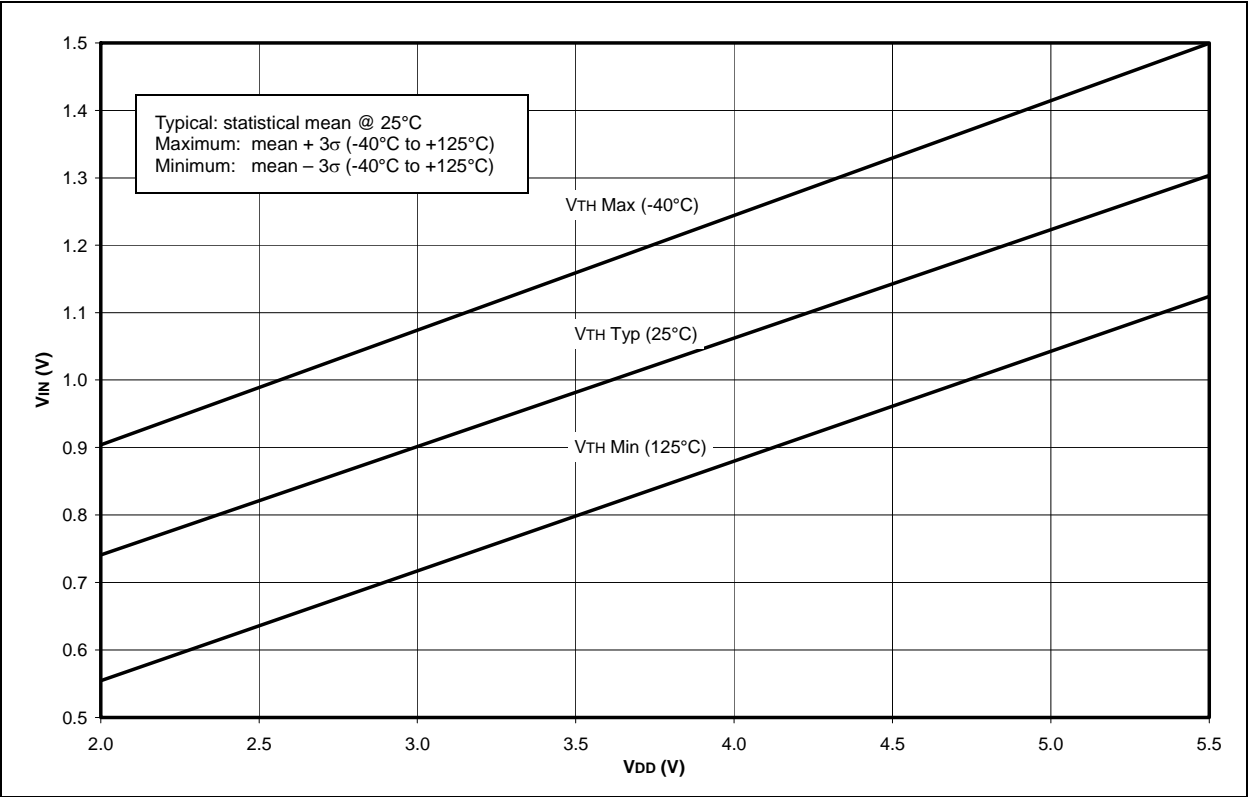
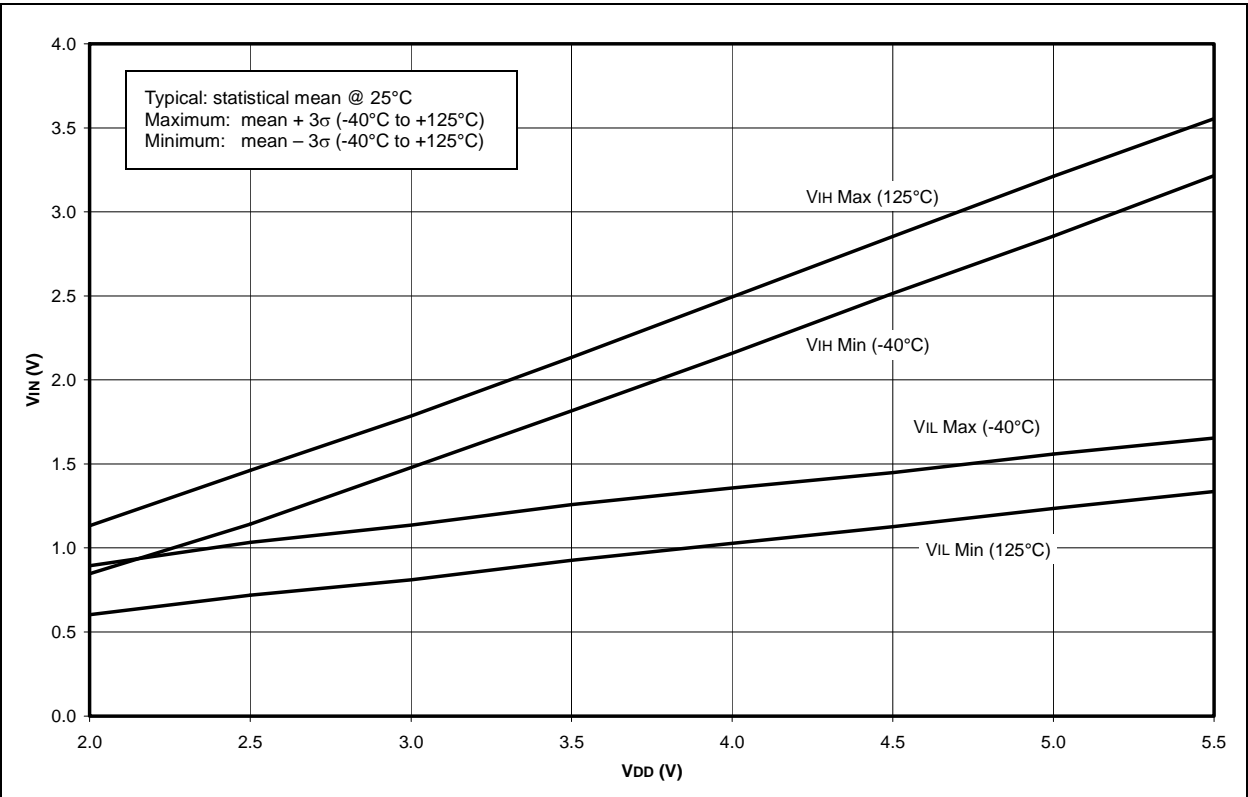


FIGURE 16-22: MINIMUM AND MAXIMUM V_{IN} vs. V_{DD} (ST INPUT, -40°C TO +125°C)

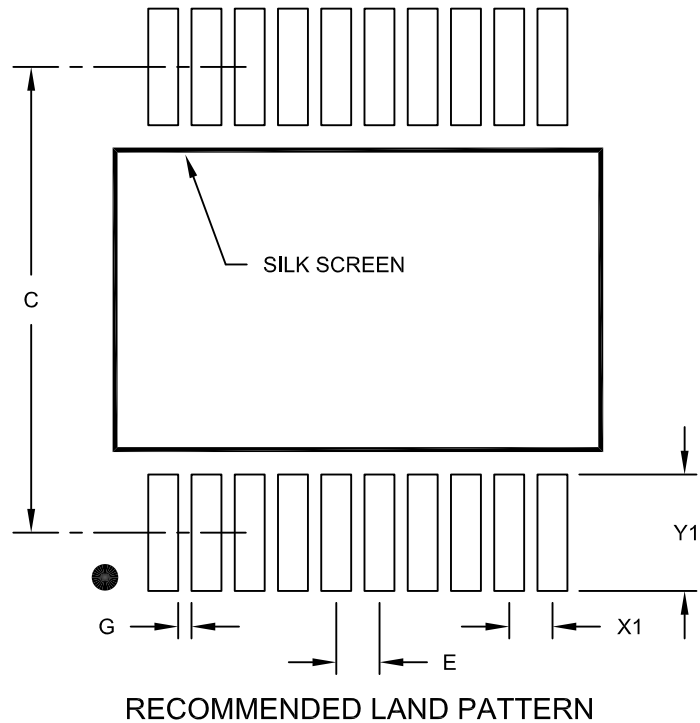


PIC16F818/819

NOTES:

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072A

PIC16F818/819

NOTES:

PIC16F818/819

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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